

Title (en)

METAL OR METAL ALLOY BASED SPUTTER TARGET AND METHOD FOR THE PRODUCTION THEREOF

Title (de)

SPUTTERTARGET AUF DER BASIS EINES METALLES ODER EINER METALLLEGIERUNG UND VERFAHREN ZU DESSEN HERSTELLUNG

Title (fr)

CIBLE DE PULVERISATION CATHODIQUE A BASE D'UN METAL OU D'UN ALLIAGE METALLIQUE, ET SON PROCEDE DE PRODUCTION

Publication

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Application

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Abstract (en)

[origin: DE10017414A1] The invention relates to metal or metal alloy based sputter target, preferably with a melting temperature of less than 750 DEG C. The invention also relates to a method for the production of a to metal or metal alloy based sputter target 750 DEG C,preferably with a melting temperature of less than 750 DEG C..

IPC 1-7

**C23C 14/34**

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